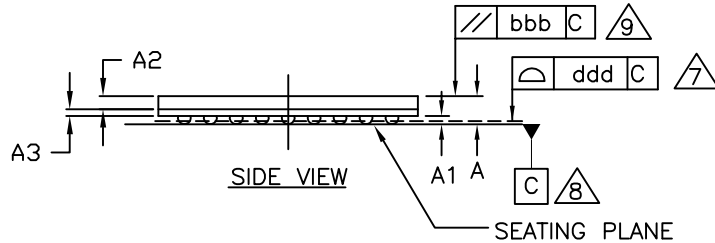
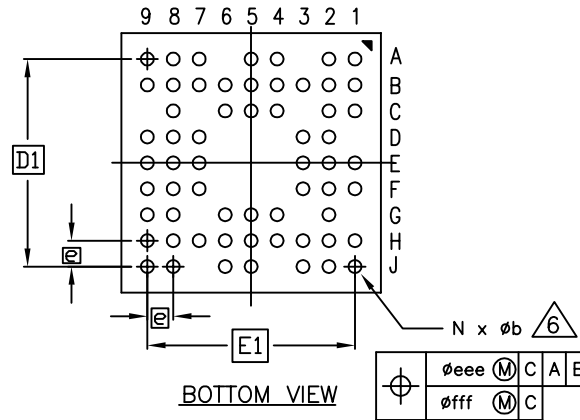
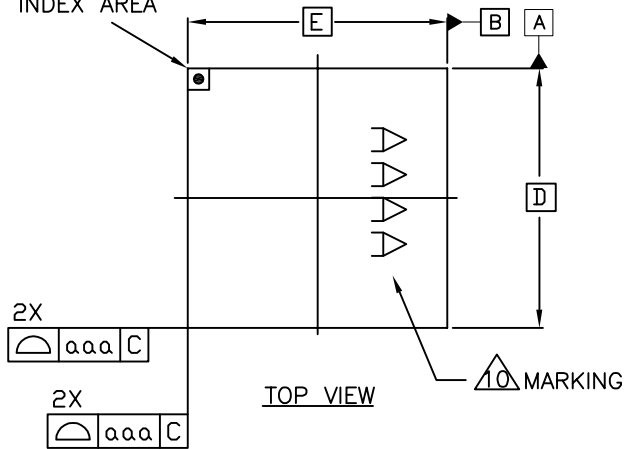


A1 CORNER INDEX AREA



	DIMENSIONAL REFERENCE		
	MIN.	NOM.	MAX.
A	0.390	0.540	0.600
A1	0.110	0.116	0.210
A2	0.250 REF		
A3	0.130 REF		
b	0.200	0.250	0.300
D	4.90	5.00	5.10
D1	4.00 BSC		
E	4.90	5.00	5.10
E1	4.00 BSC		
e	0.500 BSC.		
aaa	0.100		
bbb	0.100		
ddd	0.080		
eee	0.150		
fff	0.080		
N	61		

NOTES:

- ALL DIMENSIONS ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED.
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M 1994.
- MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC# 10-0131
- 'e' REPRESENTS THE BASIC SOLDER BALL PITCH.
- 'N' IS THE NUMBER OF ATTACHED SOLDER BALLS.
- 'b' IS MEASURABLE AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO THE PRIMARY DATUM C .
- DIMENSION 'ddd' IS MEASURED PARALLEL TO PRIMARY DATUM C .
- PRIMARY DATUM C (SEATING PLANE) IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
- MARKING SHOWN IS FOR PKG. ORIENTATION ONLY.
- ALL DIMENSIONS APPLY TO PbFREE (+) PKG. CODE.
- PKG CODE: E6155+1 (EXTREMELY THIN BGA)

-DRAWING NOT TO SCALE-

MAXIM

TITLE:
PACKAGE OUTLINE, 61 BALLS XBGA,
5x5x0.54mm, 0.5mm PITCH

APPROVAL	DOCUMENT CONTROL NO. 21-0667	REV. B	1/1
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